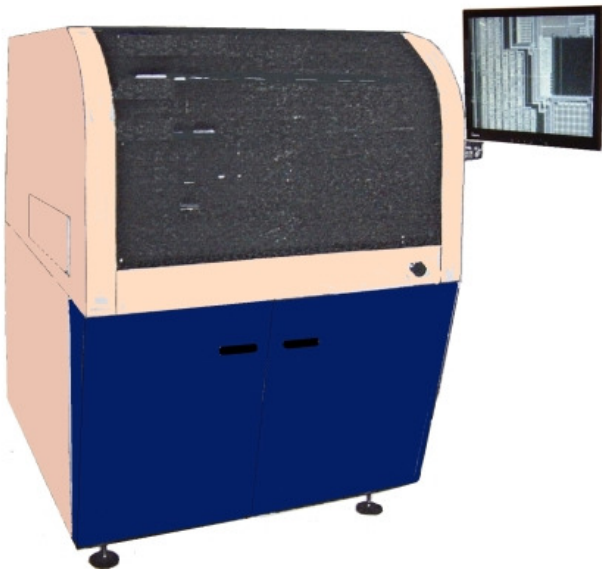


Die Sorter Platform PP410-420-430



Automatic Die Bonder

The JFP PP410 series is designed for all high density substrate based applications, such as Matrix BGA, PBGA and many others as well, as lead frame applications such as GFN/MLP.

A unique maintenance free, high speed transfert head is the heart of the system.

The PP410 series provide customers with the highest quality and best cost/performance system on the market.

Our proven expertise in bonding application effectively provides the technology and support to help our customers. The PP410 is extremely user friendly and require minimal training to operate.

Sorter

- Single Chip multi placement
- Throughput up to 3000/h
- Placement accuracy: <math><20\mu\text{m}</math>
- Die size: $200\mu\text{m} \times 200\mu\text{m}$ to $20\text{mm} \times 20\text{mm}$
- Wafer size: 6": option 8" and 12"

Wafer Station

- Wafer manual loading
- Wafer stroke + Loading
- Programmable ejection system
- Multi needle chuck, vacuum chuck
- Wafer 6" up to 300mm

Module PP 410

- High speed pick up & transfert head
- Travel lenght 300mm
- Pick up component detection
- Touch down contact detection
- Z programmable speed
- Place force programmable
- Low pressure puff-off controller
- Substrate table 100×200 mm
- Global or local alignment per position

Vision System

- Cognex 8000
- Quality reject criteria
- Crosshair and pattern on display
- Wafer mapping
- dot ink detection
- Programmable lighting oblique & vertical

Software/Application

- OS Windows XP pro
- User interface: GUI supported by expert panels
- Standard language : English

OPTIONS

- Stamping platform
- Dispenser
- Multi head configuration
- Automatic Indexer: boats, substrate, Tape.

Technical Specifications

Voltage:	100 / 230VAC 2 kva
Size:	$1200 \times 950 \times 1450$ mm
Weight:	300 kg.

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